Special Issue

Nanomanufacturing of Biomedical Systems and Devices

Message from the Guest Editors

In this Special Issue, interdisciplinary topics related to innovative top-down fabrication and manufacture of micro/nano enabled biomedical devices, mechanisms and approaches for bottom-up manipulation and assembling of nanobio devices, emerging MEMS/NEMS/bioMEMS/microfluidics for studying molecular/cellular sensing and communications with controlled environments and stimulations, as well as novel schemes of implantable devices for sensing and biochemical delivery, will be included. We welcome your contributions to this Special Issue on any of following topics:

- Nanomanufacturing
- Nanosensors
- BioMEMS
- Microfluidics
- Implantable medical devices

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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